

ABSTRACT OF THE DISCLOSURE

**IC CHIP, HEAD SUSPENSION ASSEMBLY WITH THE IC CHIP,
MANUFACTURING METHOD OF THE IC CHIP AND MANUFACTURING METHOD
OF THE HEAD SUSPENSION ASSEMBLY**

An IC chip having a front surface and a back surface opposite to the front surface includes a circuit for a thin-film magnetic head element, connection terminals of the circuit formed on the front surface, and a protection layer formed on at least a part of the back surface.

(Fig. 2)